

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.11254	100.0	0.51026
			Subtotal	0.11254	100	0.51026
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.05073	100.0	0.23
			Subtotal	0.05073	100	0.23
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00397	2.0	0.018
	Lead alloy	Silver (Ag)	7440-22-4	0.00496	2.5	0.0225
	Lead alloy	Lead (Pb)	7439-92-1	0.18956	95.5	0.8595
			Subtotal	0.19849	100	0.9
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01153	0.03	0.05226
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01153	0.03	0.05226
	Copper alloy	Iron (Fe)	7439-89-6	0.03842	0.1	0.1742
	Copper alloy	Copper (Cu)	7440-50-8	38.35763	99.84	173.92128
			Subtotal	38.41911	100	174.2
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.22576	3.8	10.09204
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.51436	6.0	15.9348
	Filler	Silica fused	60676-86-0	52.71533	90.0	239.022
	Carbon Black	Carbon black	1333-86-4	0.11715	0.2	0.53116
			Subtotal	58.5726	100	265.58
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.64655	100.0	12
			Subtotal	2.64655	100	12
			Total	100.00002	100	453.42026

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